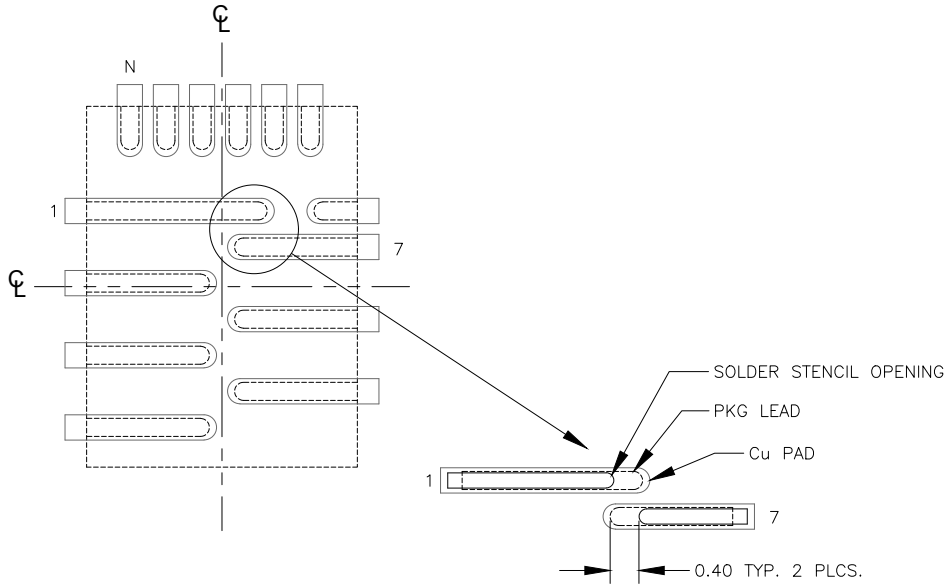
APPENDIX

SOLDER STENCIL RECOMMENDATION (LEADS 1 AND 7)



—DRAWING NOT TO SCALE—

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.
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